

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
-12V	14.8mΩ @ V _{GS} = -4.5V	-9.5A
	19mΩ @ V _{GS} = -2.5V	-8.5A
	26mΩ @ V _{GS} = -1.8V	-7.2A
	32mΩ @ V _{GS} = -1.5V	-6.6A

Description

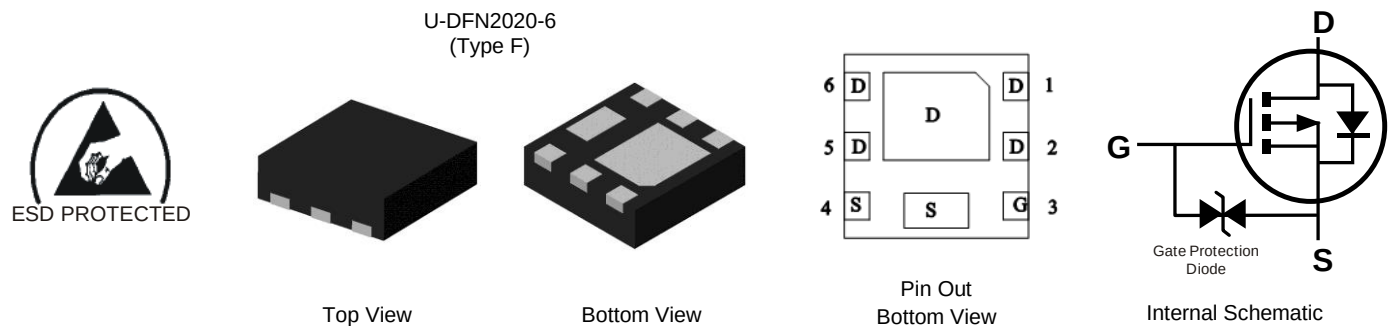
This MOSFET is designed specifically for use in battery management applications.

Features

- 0.6mm Profile – Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- ESD Protected Gate
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](mailto:contact@diodes.com) or your local Diodes representative.
<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.0065 grams (Approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP1022UFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMP1022UFDF-13	U-DFN2020-6 (Type F)	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-12	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	-9.5 -7.6	A
	t < 5s	T _A = +25°C T _A = +70°C	I _D	-11.0 -8.8	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-90	A
Continuous Source-Drain Diode Current		T _A = +25°C T _C = +25°C	I _S	-2.5 -7.1	A
Pulsed Source-Drain Diode Current (10µs Pulse, Duty Cycle = 1%)			I _{SM}	-50	A

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	P _D	0.73	W
	T _A = +70°C		0.47	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{θJA}	172	°C/W
	t < 5s		128	
Total Power Dissipation (Note 6)	T _A = +25°C	P _D	2.1	W
	T _A = +70°C		1.3	
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{θJA}	59	°C/W
	t < 5s		45	
Thermal Resistance, Junction to Case (Note 6)	Steady State	R _{θJC}	5.1	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-12	—	—	V	V _{GS} = 0V, I _D = -250µA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	-200	nA	V _{DS} = -12V, V _{GS} = 0V
Zero Gate Voltage Drain Current T _J = +55°C (Note 8)	I _{DSS}	—	—	-2	µA	V _{DS} = -12V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±10	µA	V _{GS} = ±8V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-0.35	—	-0.8	V	V _{DS} = V _{GS} , I _D = -250µA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	12	14.8	mΩ	V _{GS} = -4.5V, I _D = -4A
			15	19		V _{GS} = -2.5V, I _D = -4A
			20	26		V _{GS} = -1.8V, I _D = -4A
			23	32		V _{GS} = -1.5V, I _D = -2A
Diode Forward Voltage	V _{SD}	—	-0.8	-1.2	V	V _{GS} = 0V, I _S = -8A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	2,712	—	pF	V _{DS} = -10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	514	—		
Reverse Transfer Capacitance	C _{rss}	—	467	—		
Gate Resistance	R _g	—	8.6	18	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	—	48.3	—	nC	V _{GS} = -8V, V _{DS} = -6V, I _D = -10A
Total Gate Charge	Q _g	—	28.6	—		
Gate-Source Charge	Q _{gs}	—	4.2	—		
Gate-Drain Charge	Q _{gd}	—	7.0	—		
Turn-On Delay Time	t _{D(ON)}	—	25.1	—	ns	V _{DS} = -6V, V _{GS} = -4.5V, R _G = 1Ω, I _D = -8A
Turn-On Rise Time	t _R	—	39.8	—		
Turn-Off Delay Time	t _{D(OFF)}	—	141	—		
Turn-Off Fall Time	t _F	—	147	—		

- Notes:
5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing.

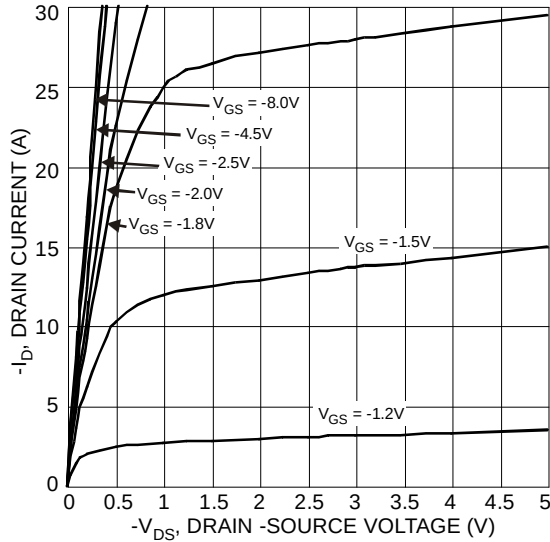


Figure 1 Typical Output Characteristics

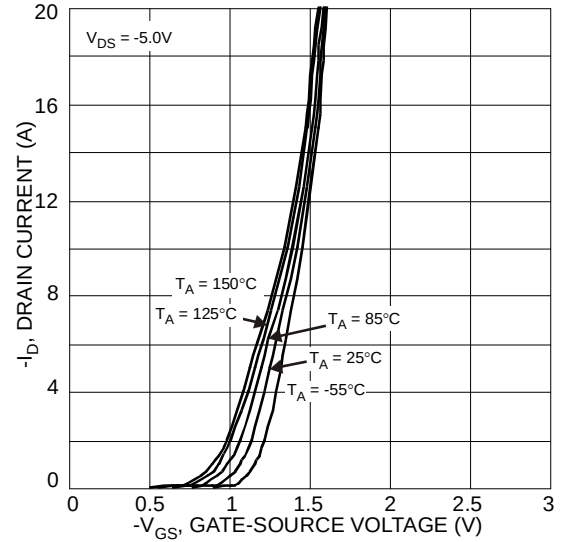


Figure 2 Typical Transfer Characteristics

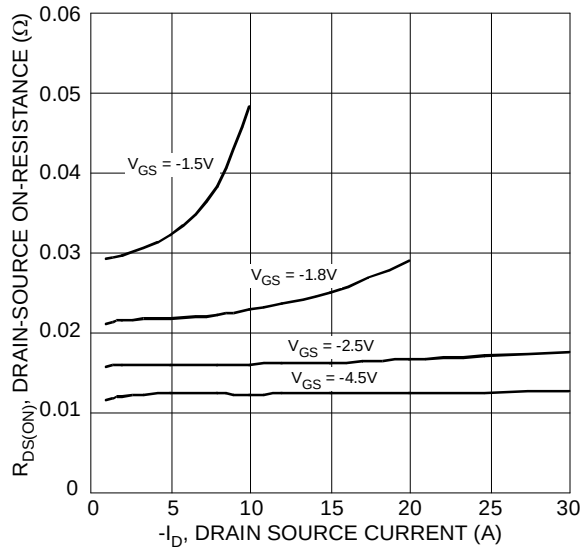


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

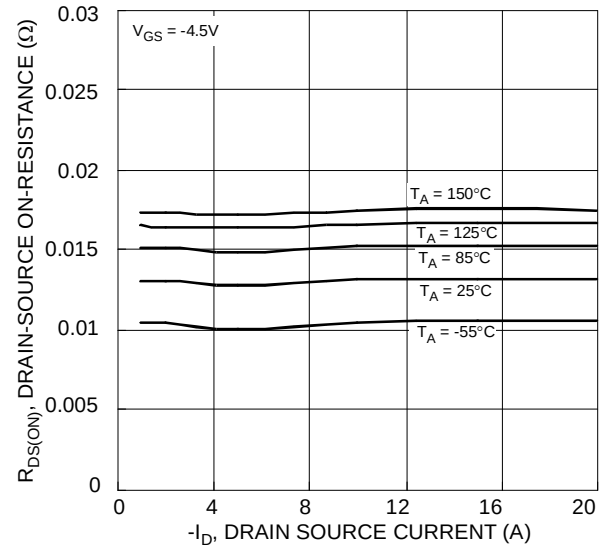


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

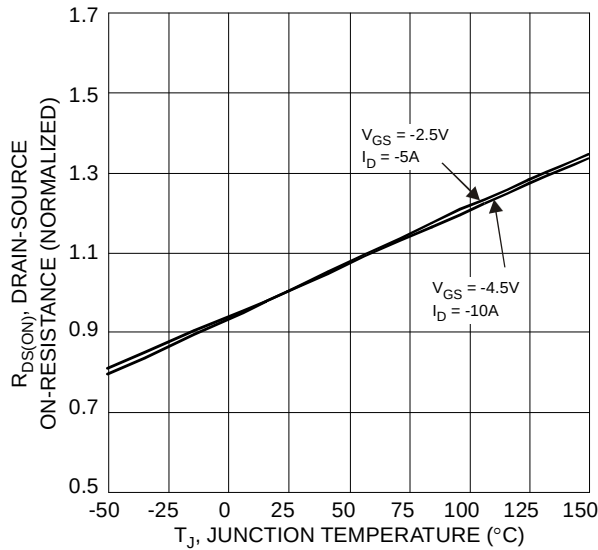


Figure 5 On-Resistance Variation with Temperature

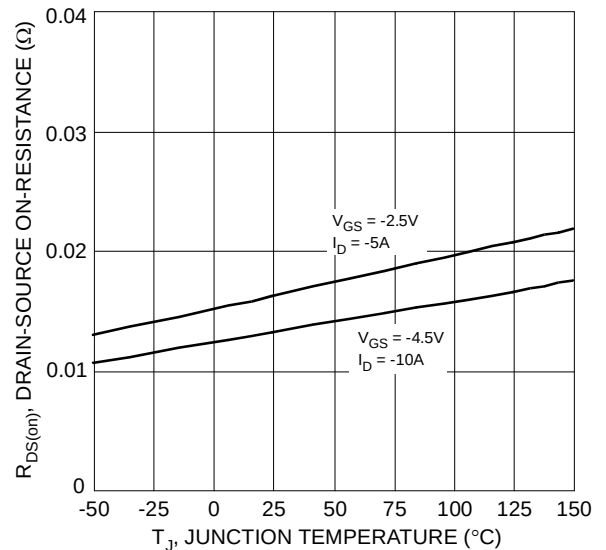


Figure 6 On-Resistance Variation with Temperature

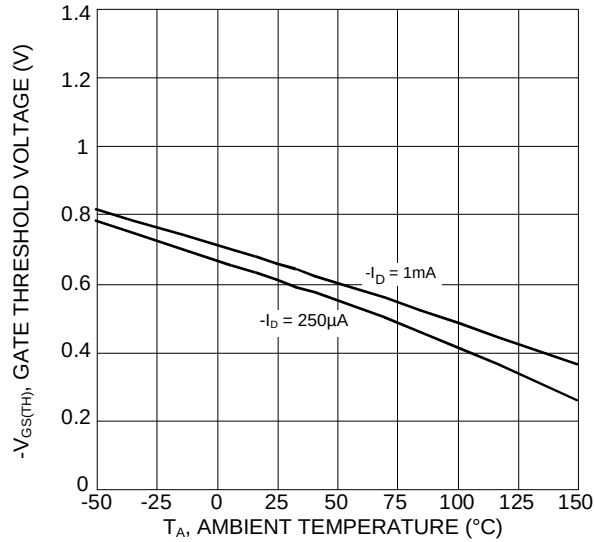


Figure 7 Gate Threshold Variation vs. Ambient Temperature

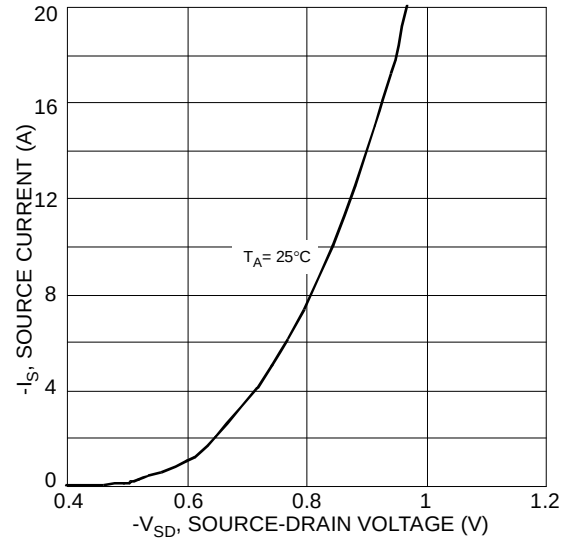


Figure 8 Diode Forward Voltage vs. Current

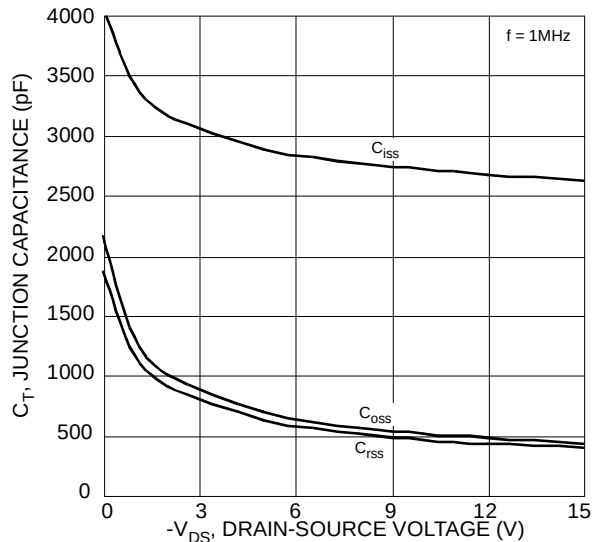


Figure 9 Typical Junction Capacitance

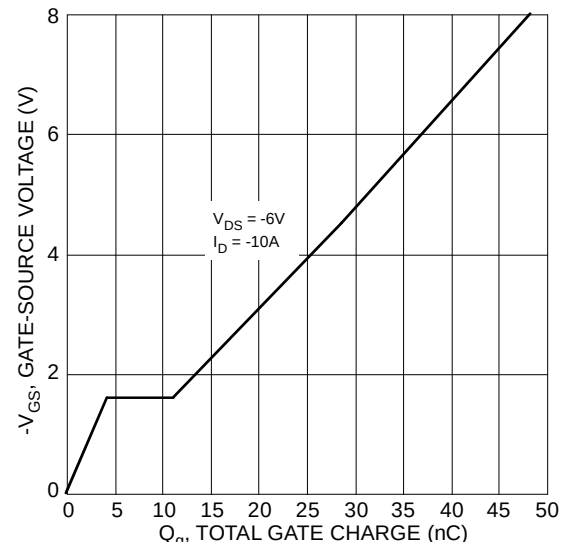


Figure 10 Gate-Charge Characteristics

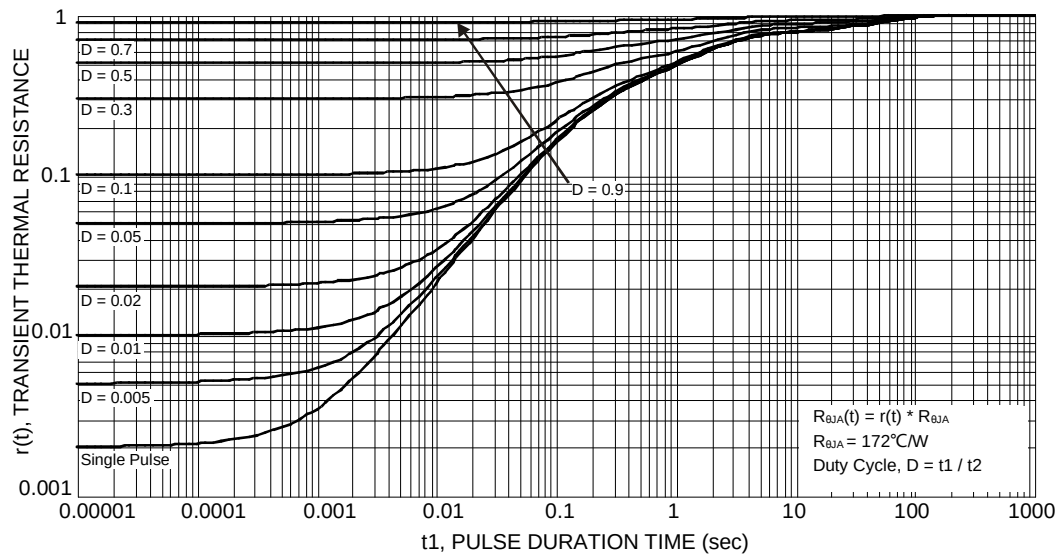
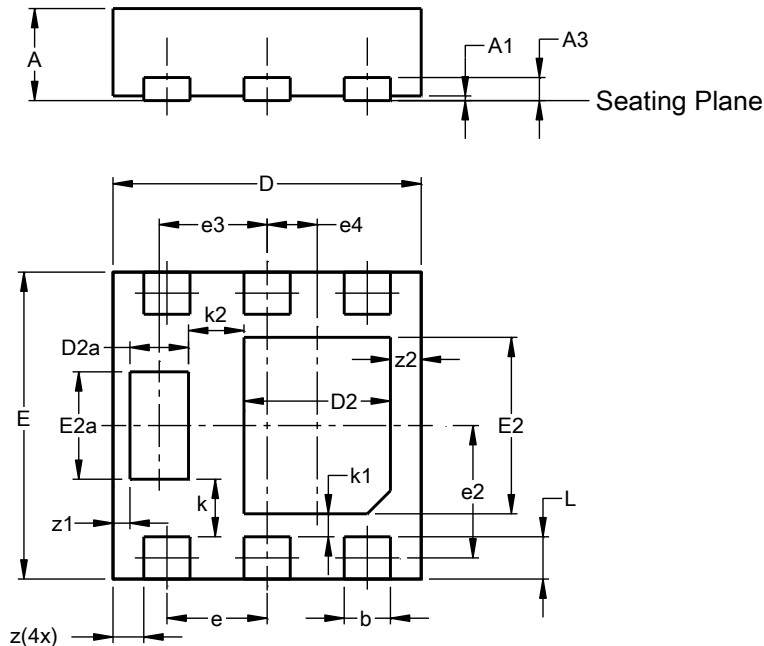


Figure 11 Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)

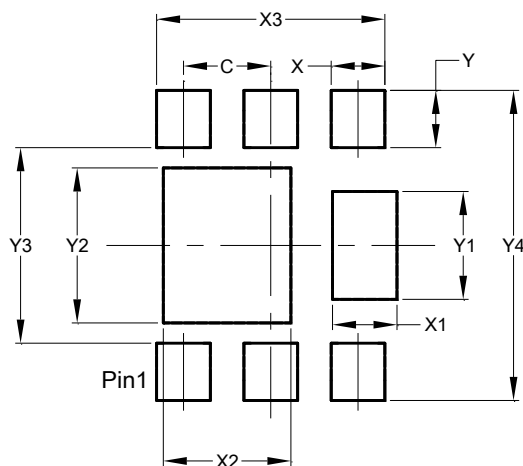


U-DFN2020-6 (Type F)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.03
A3	-	-	0.15
b	0.25	0.35	0.30
D	1.95	2.05	2.00
D2	0.85	1.05	0.95
D2a	0.33	0.43	0.38
E	1.95	2.05	2.00
E2	1.05	1.25	1.15
E2a	0.65	0.75	0.70
e	0.65 BSC		
e2	0.863 BSC		
e3	0.70 BSC		
e4	0.325 BSC		
k	0.37 BSC		
k1	0.15 BSC		
k2	0.36 BSC		
L	0.225	0.325	0.275
z	0.20 BSC		
z1	0.110 BSC		
z2	0.20 BSC		
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)
C	0.650
X	0.400
X1	0.480
X2	0.950
X3	1.700
Y	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300

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